

Heat sink compound

non-silicone

Type series MT8800



Features

- Non-silicone product
- Better heat transfer than silicone-based products
- No solder bath contamination
- Very low bleed and evaporation value
- Compatible with metal and plastic components
- Wide temperature range
- Non toxic
- Will not melt, dry or harden
- Meets KS 21343 spec and Military Specification MIL-C-47113B

Application

The non-silicone heat sink compound was created to solve the problems of contamination and migration associated with silicone-based products. The compound is a unique synthetic-based thermal grease used to insure quick, efficient heat transfer and dissipation.

The primary advantage of this non-silicone product is long-term material stability. Virtually no bleed or evaporation over a wide operating temperature range - even in a vacuum atmosphere (10-5 tor/mil, 24 hrs. at 100°C). Compound will not leach, dry, harden, or melt in normal industrial use.

Technical data

Consistency

320 (Penetration, worked, 60x)
per ASTM D-217

Specific gravity

2,7 g /cm³ at 25 °C
per ASTM D-70

Bleed

0.1 %/Wt. at 200 °C/24h
FTM-321 modified

Evaporation

0.6 %/Wt. at 200 °C/24h
FTM-321 modified

Thermal Conductivity at 36 °C

0.70 W/m °K
16.7 x 10⁻⁴ Cal/sec cm °C
4.8 BTU.In (h/FT².°F)
"hot wire" method per
MIL-C-47113B

Electrical properties

305 V/mil dielectric strength 0.05" gap
per ASTM D-149
4.50 dielectric constant, 25 °C at
1000 Hz per ADTM D-150
32 ppm/°C coefficient of thermal
expansion
1.65 x 10¹⁴ Ohm/cm volume resistivity
per ASTM D-257

Operating temperature range

-40...200 °C

Appearance

white paste

Order details

Heat sink compound, non-silicone	MT8800	
injection, 3 g contents		A1
order code:	MT8800	A1